

## High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology

VSMY2943RGX01

VSMY2943GX01



### LINKS TO ADDITIONAL RESOURCES



### DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2943 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.55
- AEC-Q101 qualified
- Peak wavelength:  $\lambda_p = 940$  nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity:  $\phi = \pm 28^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2503X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

### APPLICATIONS

- Automotive sensors
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination
- [Head-up displays](#)

AUTOMOTIVE  
GRADE

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
**GREEN**  
(5-2008)

### PRODUCT SUMMARY

COMPONENT	$I_e$ (mW/sr)	$\phi$ (°)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY2943RGX01	50	$\pm 28$	940	10
VSMY2943GX01	50	$\pm 28$	940	10

#### Note

- Test conditions see table "Basic Characteristics"

### ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2943RGX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2943GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

#### Note

- MOQ: minimum order quantity

**ABSOLUTE MAXIMUM RATINGS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.5$ , $t_p = 100\text{ }\mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	$I_{FSM}$	1	A
Power dissipation		$P_V$	180	mW
Junction temperature		$T_j$	100	$^{\circ}\text{C}$
Operating temperature range		$T_{amb}$	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	Acc. figure 7, J-STD-020	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	$R_{thJA}$	250	K/W

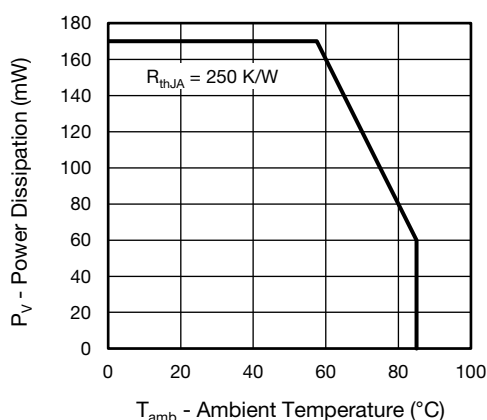


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

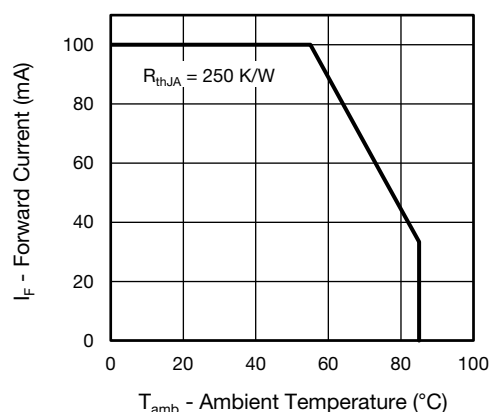


Fig. 2 - Forward Current Limit vs. Ambient Temperature

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$V_F$	-	1.4	1.8	V
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$V_F$	-	2.5	-	V
Temperature coefficient of $V_F$	$I_F = 100\text{ mA}$	$TK_{VF}$	-	-0.7	-	mV/K
Reverse current		$I_R$	not designed for reverse operation			$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0\text{ mW/cm}^2$	$C_J$	-	55	-	pF
Radiant intensity	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$I_e$	27	50	75	mW/sr
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$I_e$	-	350	-	mW/sr
Radiant power	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$\phi_e$	-	55	-	mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	$TK_{\phi_e}$	-	-0.2	-	%/K
Angle of half intensity		$\phi$	-	$\pm 28$	-	$^{\circ}$
Peak wavelength	$I_F = 100\text{ mA}$	$\lambda_p$	920	940	960	nm
Spectral bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$	-	50	-	nm
Temperature coefficient of $\lambda_p$	$I_F = 100\text{ mA}$	$TK_{\lambda_p}$	-	0.25	-	nm/K
Rise time	$I_F = 100\text{ mA}$ , 10 % to 90 %	$t_r$	-	10	-	ns
Fall time	$I_F = 100\text{ mA}$ , 10 % to 90 %	$t_f$	-	10	-	ns

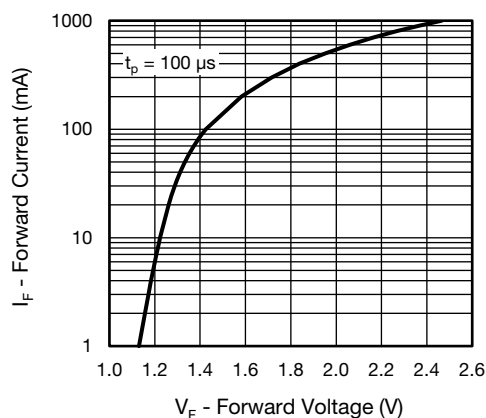
**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

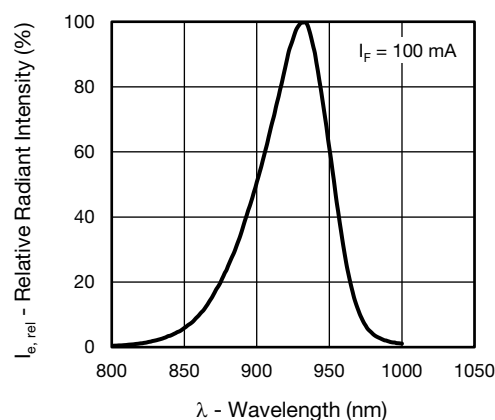


Fig. 5 - Relative Radiant Power vs. Wavelength

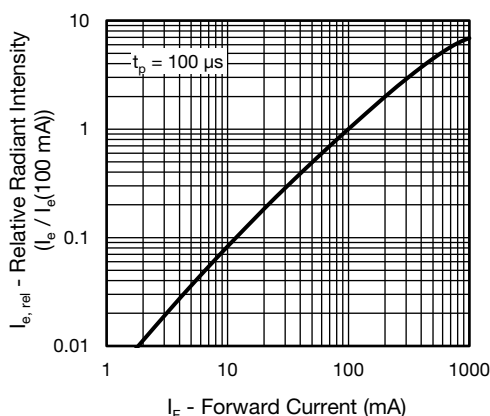
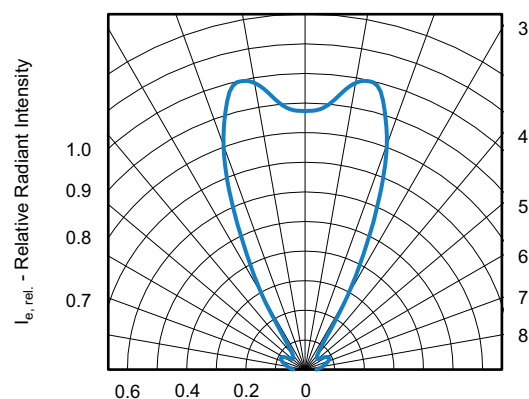
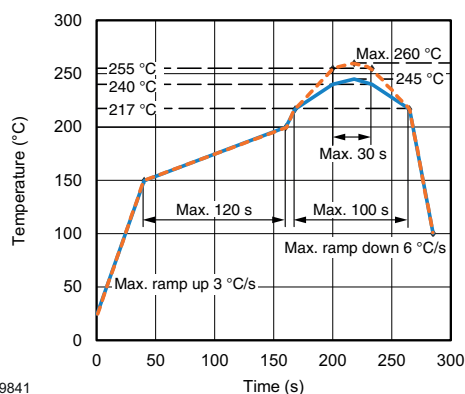


Fig. 4 - Radiant Intensity vs. Forward Current



22688

Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

**SOLDER PROFILE**


19841

Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

**FLOOR LIFE**

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ , RH < 60 %

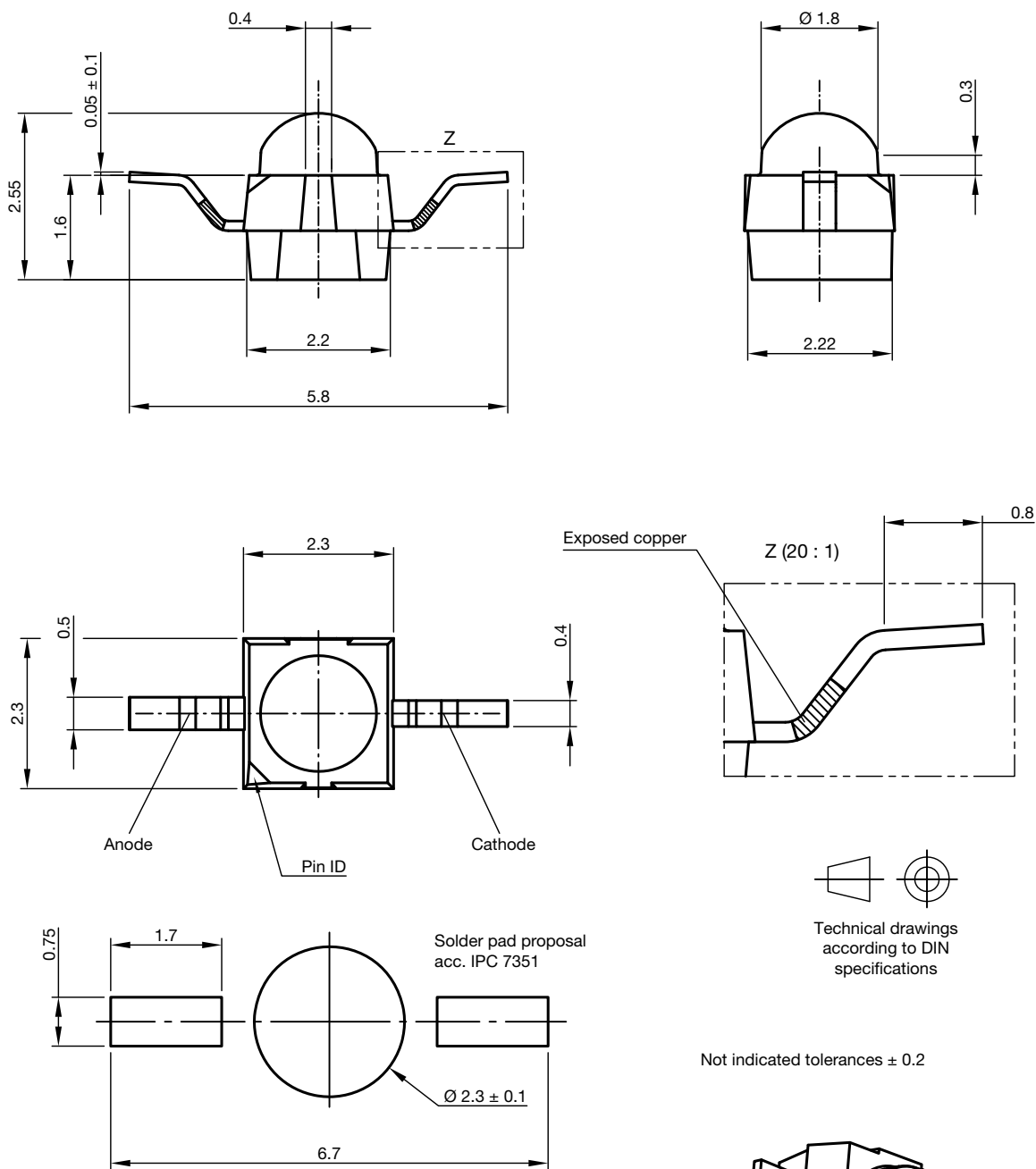
Moisture sensitivity level 2a, acc. to J-STD-020.

**DRYING**

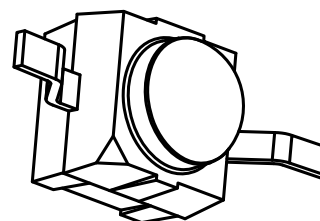
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



## PACKAGE DIMENSIONS in millimeters: VSMY2943RGX01

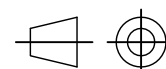
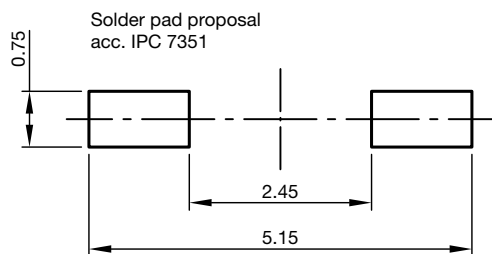
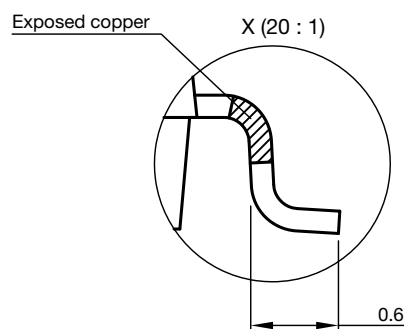
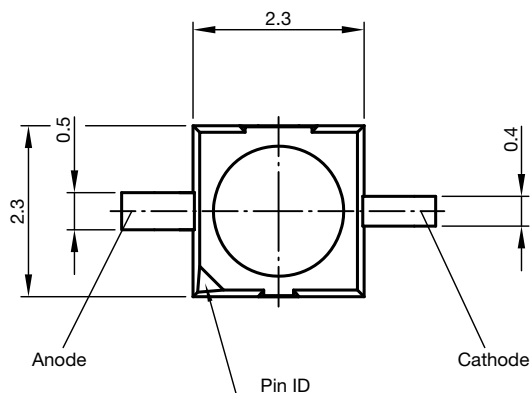
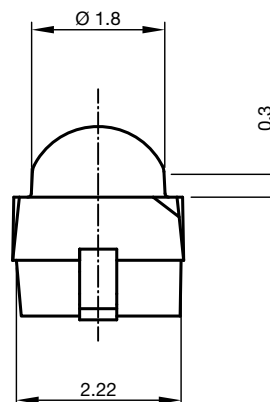
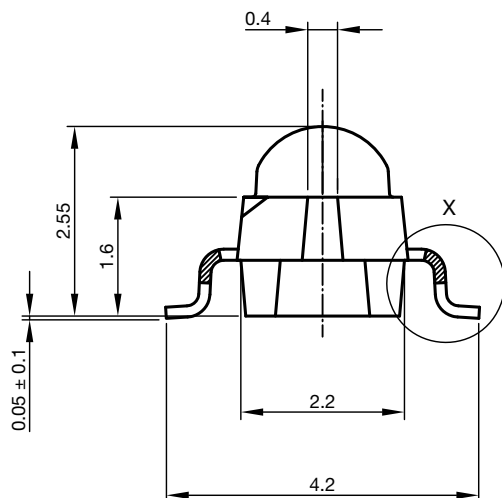


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Issue: 3; 02.10.15



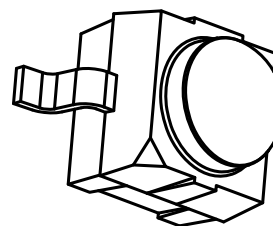


## PACKAGE DIMENSIONS in millimeters: VSMY2943GX01

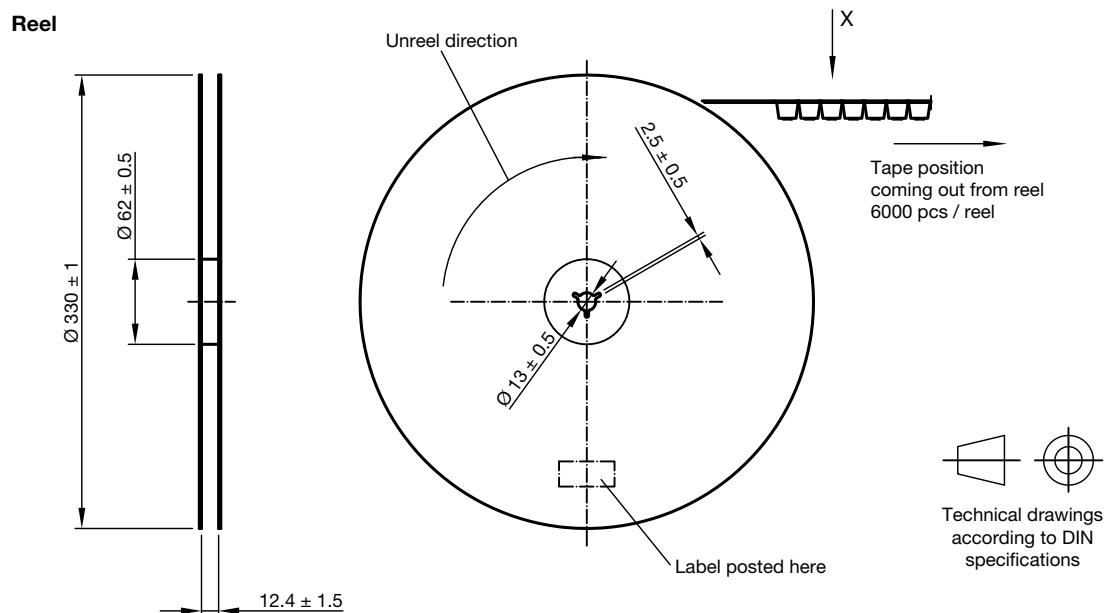
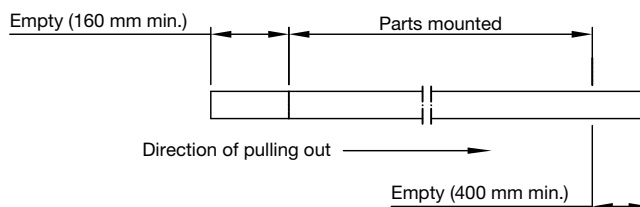


Technical drawings  
according to DIN  
specifications

Not indicated tolerances  $\pm 0.2$

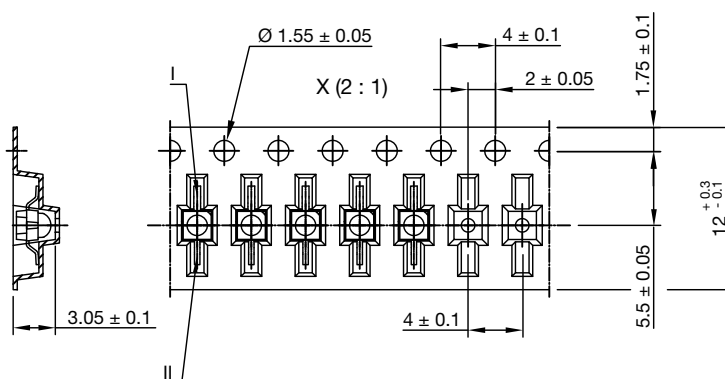


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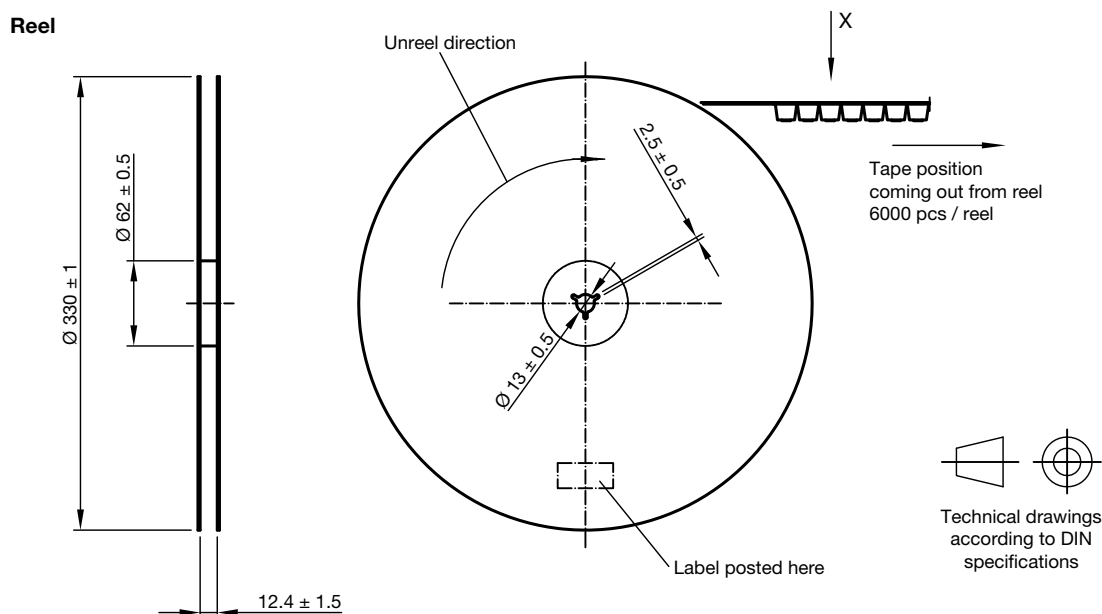
**TAPING AND REEL DIMENSIONS** in millimeters: **VSMY2943RGX01**

**Leader and trailer tape**

**Terminal position in tape**

Device	Lead I	Lead II
VSMB2943RGX01	Cathode	Anode
VSMF2893RGX01		
VEMD2x03X01	Collector	Emitter
VEMT2x03X01		
VSMY2xxx	Anode	Cathode

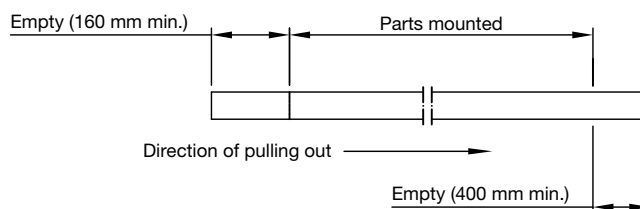
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Issue: prel.; 11.07.19



**TAPING AND REEL DIMENSIONS** in millimeters: **VSMY2943GX01**

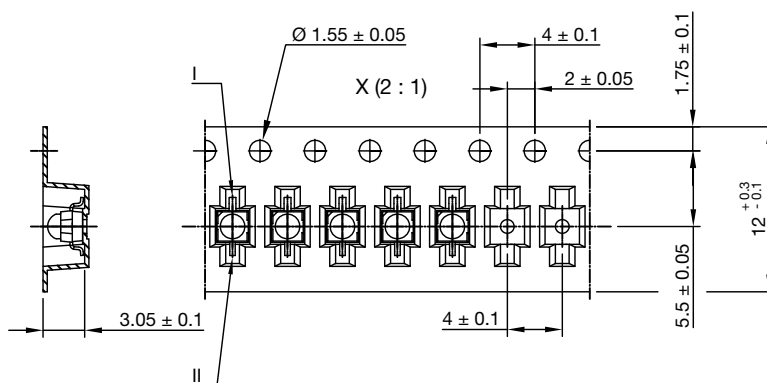


## Leader and trailer tape



### Terminal position in tape

Device	Lead I	Lead II
VSMB2943GX01	Cathode	Anode
VSMF2893GX01		
VEMD2x23X01		
VENT2x23X01	Collector	Emitter
VSMT2xxx	Anode	Cathode



Drawing-No.: 9.800-5091.21-4  
Issue: prel.; 11.07.19



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